

# Design studies of a low power serial data link for a possible upgrade of the CMS pixel detector

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Pixel Replacement/Upgrade Discussion Meeting

# Motivation

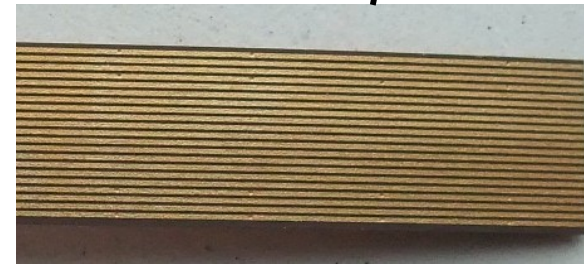
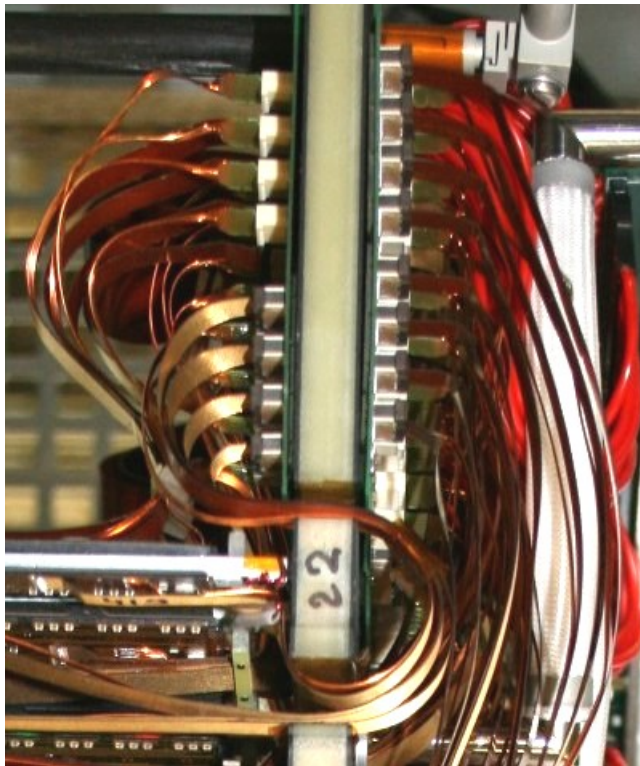
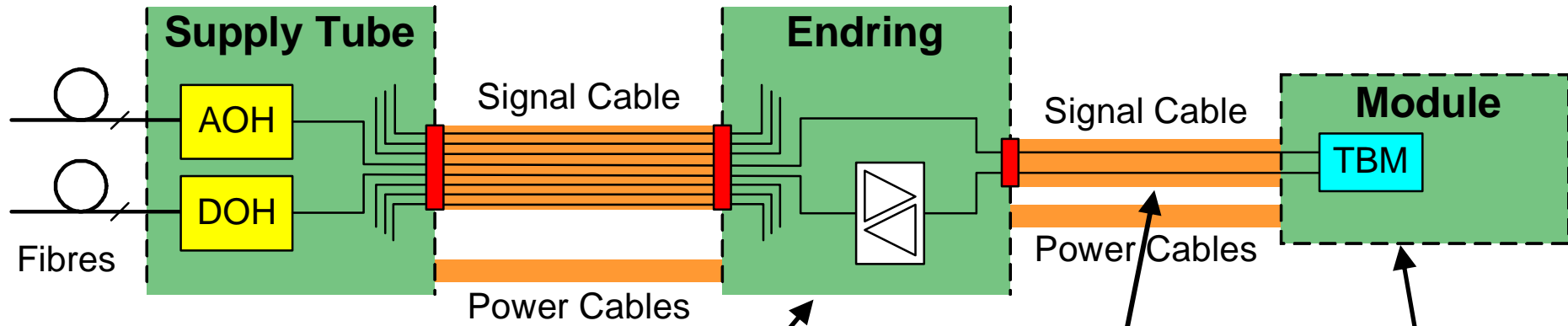
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Communication link between detector (pixel module) to outside the tracker volume (BPIX supply tube) with

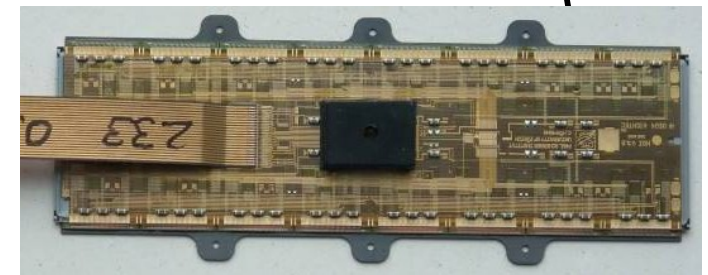
- minimal material budget → **micro twisted pair (unshielded)**
- minimal power consumption → **low voltage swing** → differential
- minimal wiring effort (# cables) → **serial data link**
- 160 or 320 Mbit/s (4x or 8x LHC clock)
- 1...2 m cable length

What is possible ?

# Existing Data Link in CMS Pixel Detector

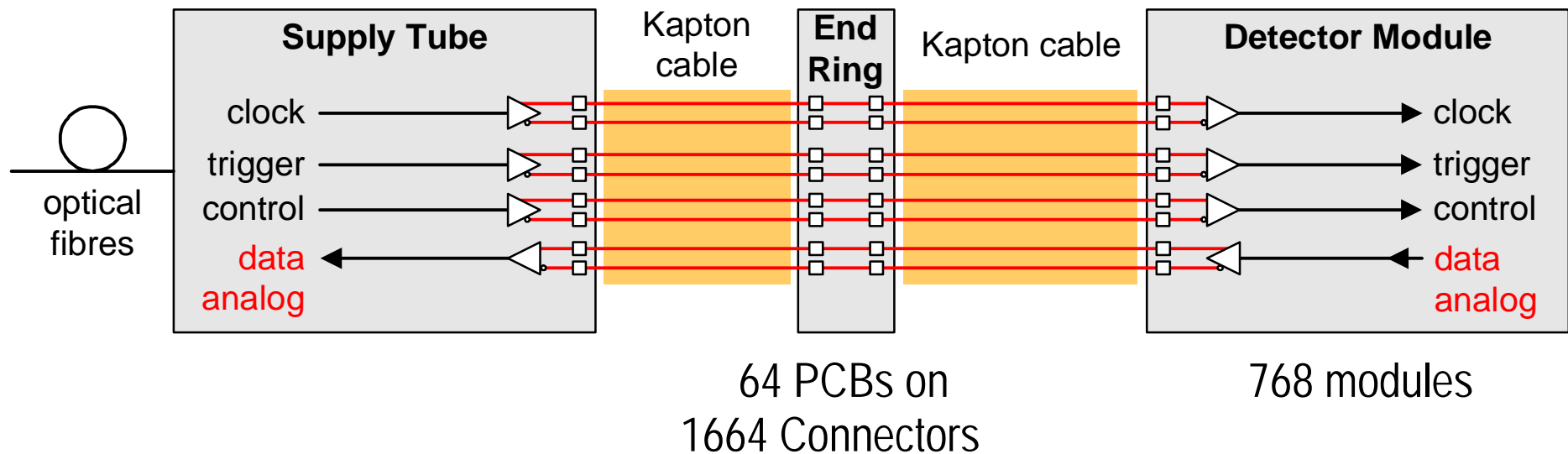


Kapton cable with 21 traces and ground plane

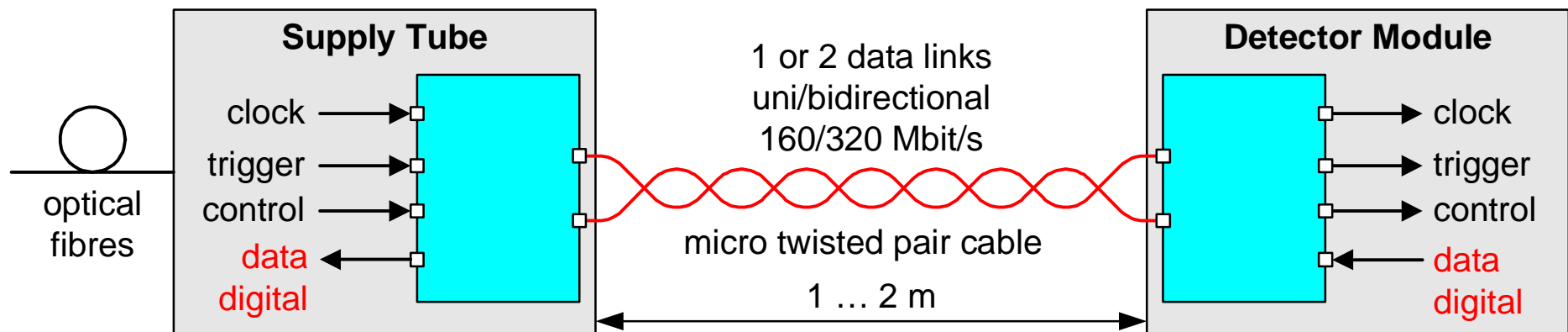


# Comparison to a possible new Concept

## Existing System in CMS Pixel Detector

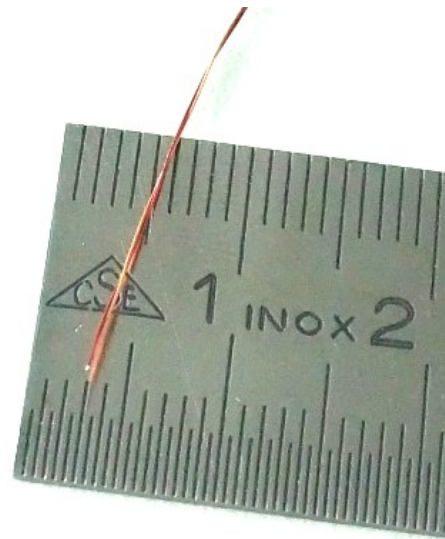
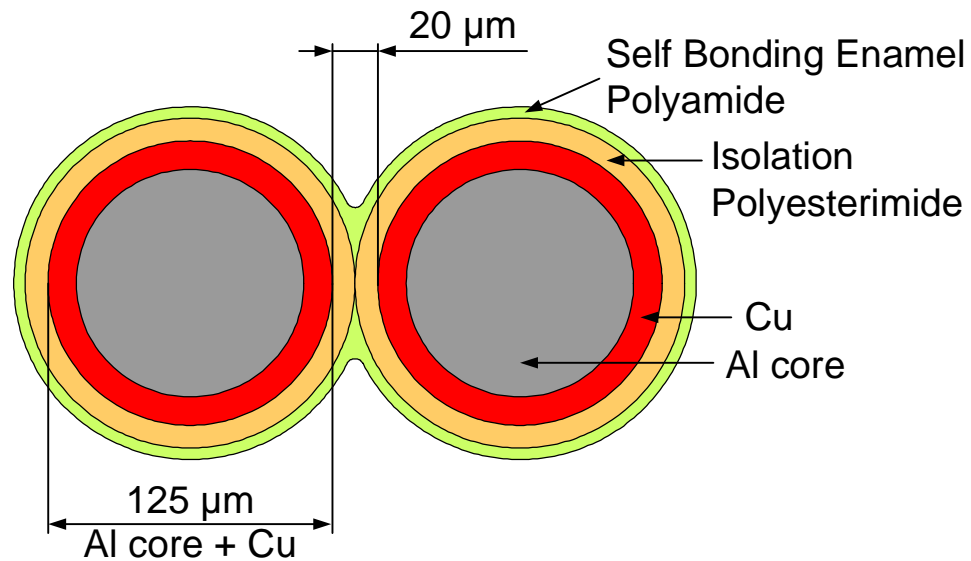


## New Concept



# Micro Twisted Pair Cable

cross section



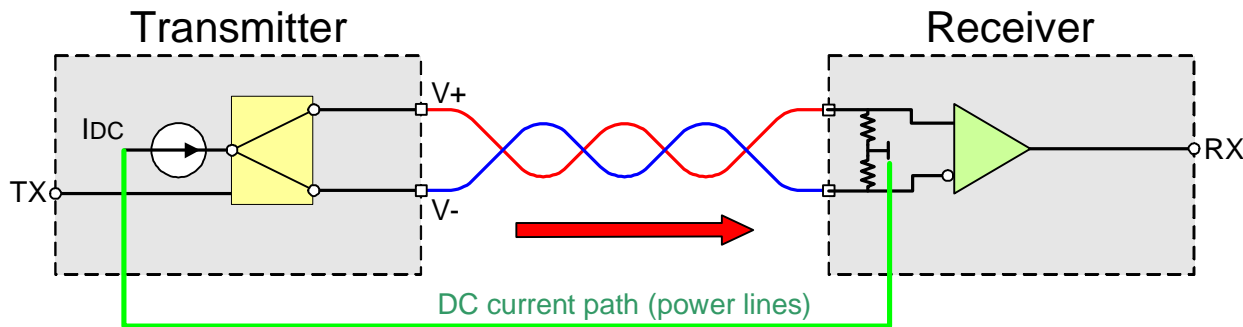
First Choice:

- twisted pair self bonding wire
- 125  $\mu\text{m}$  wire diameter (4um Cu)
- 10 mm per turn

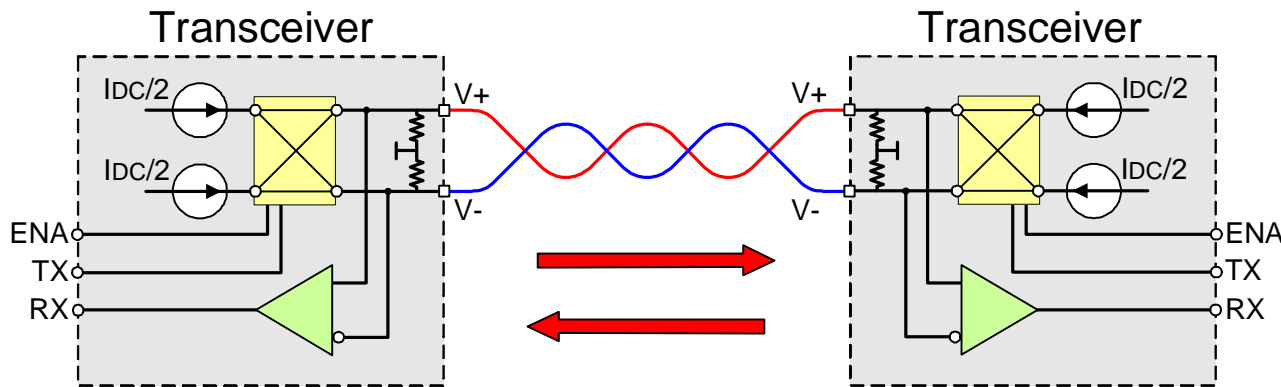
Electrical characteristics:

- Impedance: 50 Ohms (very low)
- $v = 2/3 c_0$  (5 ns/m)
- $C = 100 \text{ pF/m}$ ,  $L=250 \text{ nH/m}$
- $R_{\text{DC}} = 2.3 \text{ Ohm/m}$
- Skin depth = 8.5  $\mu\text{m}$  @ 100 MHz
- $R = 8.5 \text{ Ohm/m}$  @ 100 MHz
- 50% power loss (2 m cable)

# Data Link Configurations



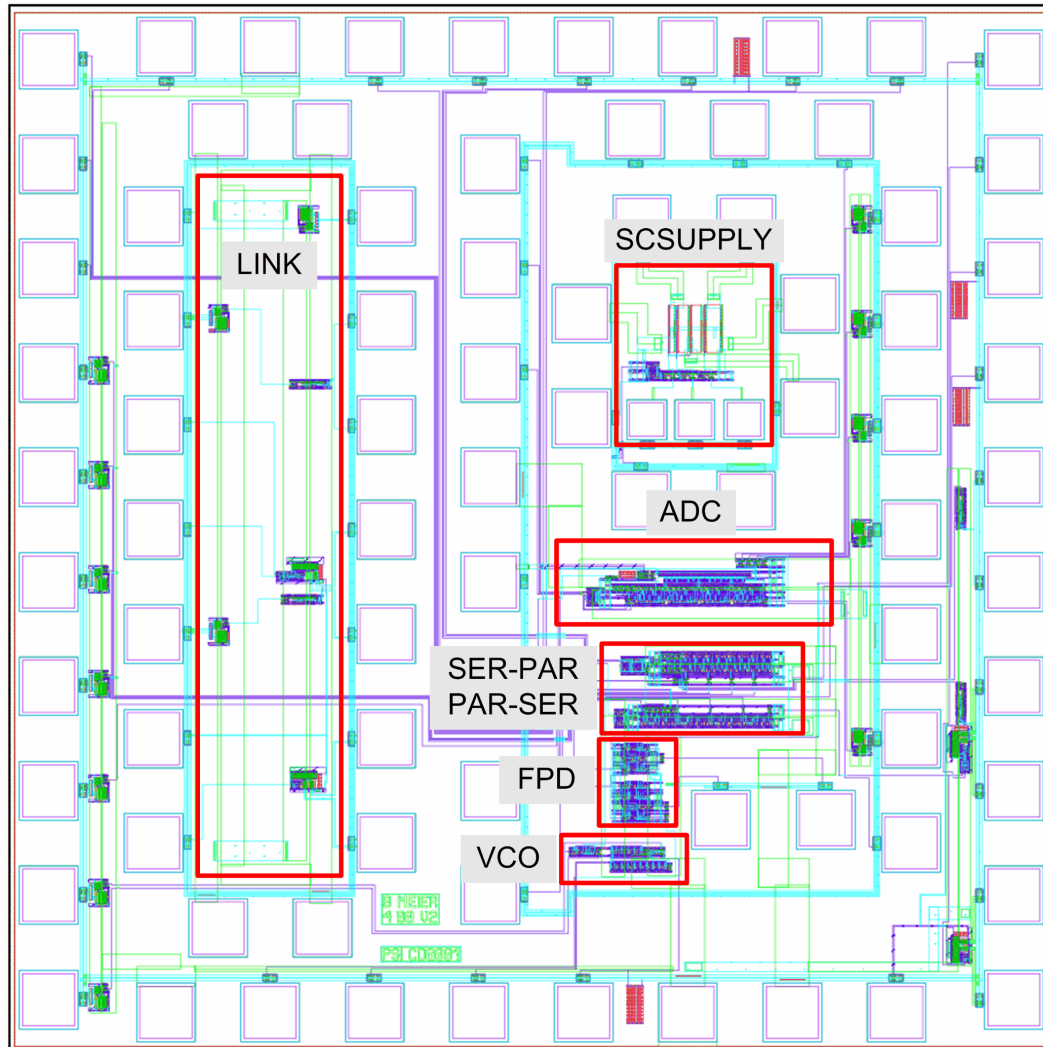
- Differential Current Driver (LCDS) from CMS Pixel
- rise time < 400 ps
- DC loop closed over power lines
- uni/bidirectional
- for test: output signal adjustable with  $I_{DC}$



Logic Levels

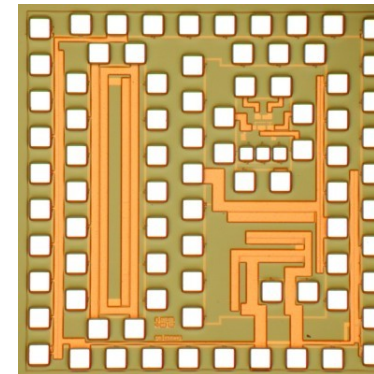
	V+	V-	diff	sum
L	0	$I_{DC}$	$-I_{DC}$	$I_{DC}$
H	$I_{DC}$	0	$+I_{DC}$	$I_{DC}$
high Z	$I_{DC}/2$	$I_{DC}/2$	0	$I_{DC}$

# Test Chip Layout



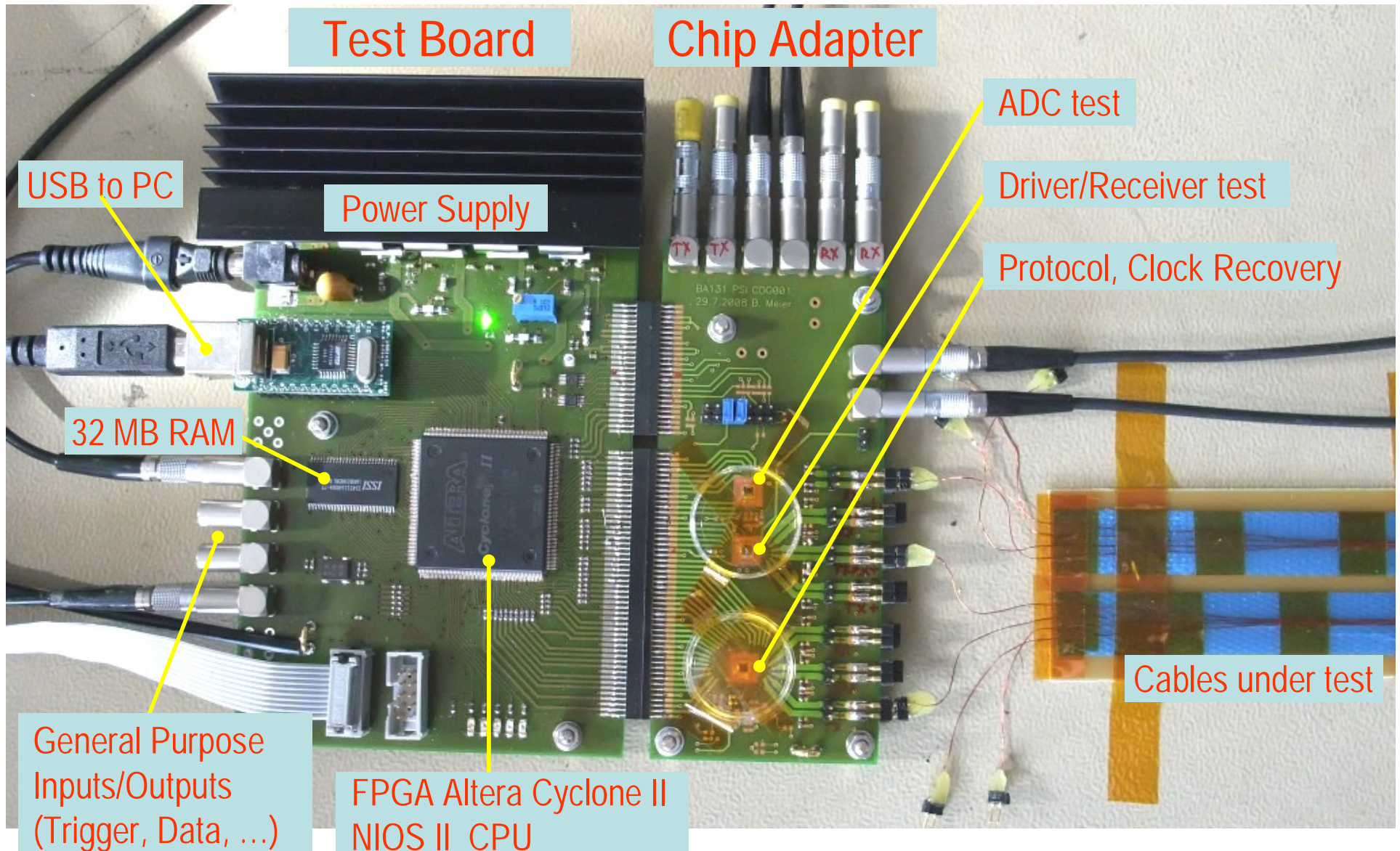
Design of a first test chip  
(PSI Chip Design Core Team)

- Size: 2 x 2 mm
- Technology: 250 nm CMOS IBM same as CMS Pixel ROC
- radiation hardness design
- CERN MPW submitted in April 2008
- design time was 4 weeks



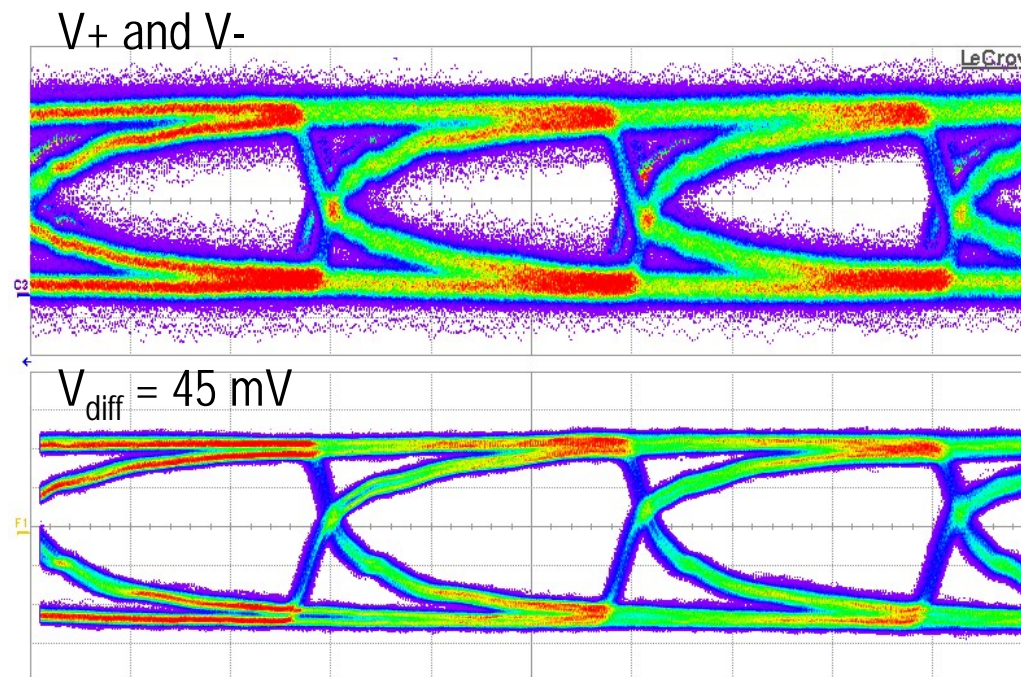


# Chip Test System



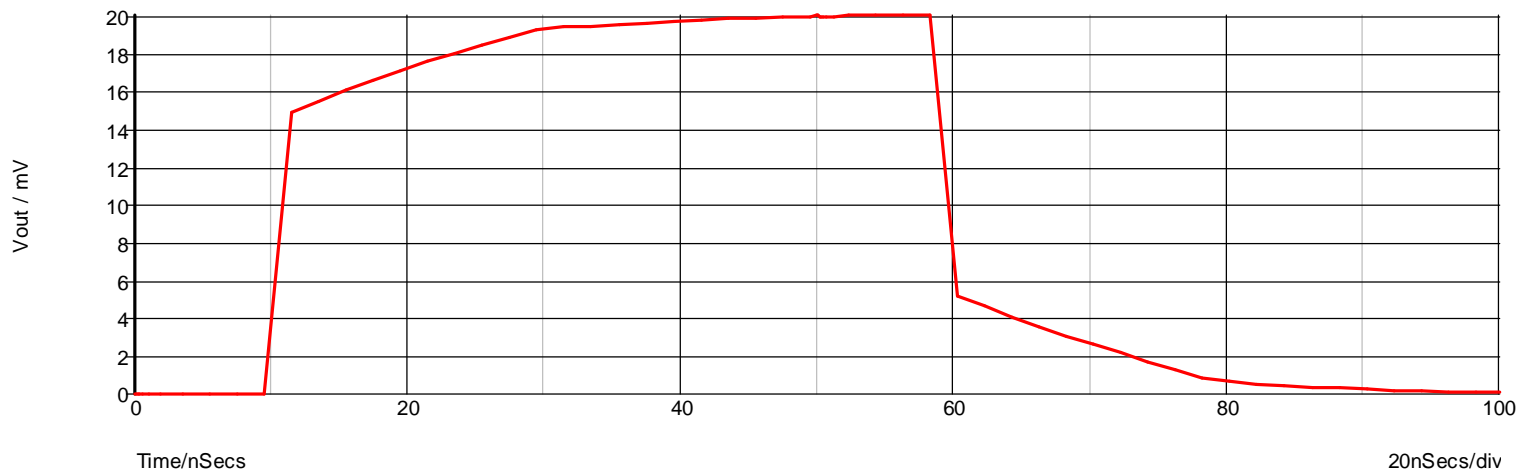


# Loss Effects at 160 Mbit/s

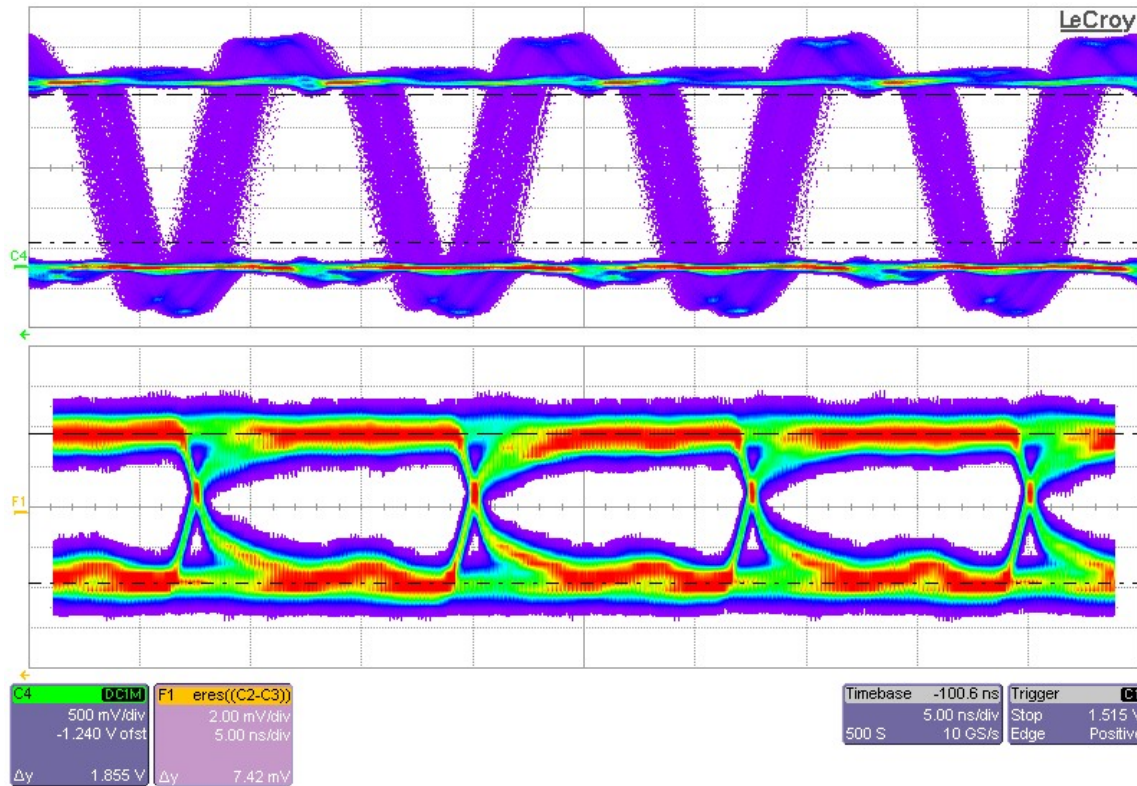


- Line length: 2 m
- Lossy line effects visible (rising and falling edges)
- Line in the RC (low frequency) and LC (high frequency) region

Fast and slow region in rising/falling edge as a result of the lossy line



# Bit Error Rate Measurements



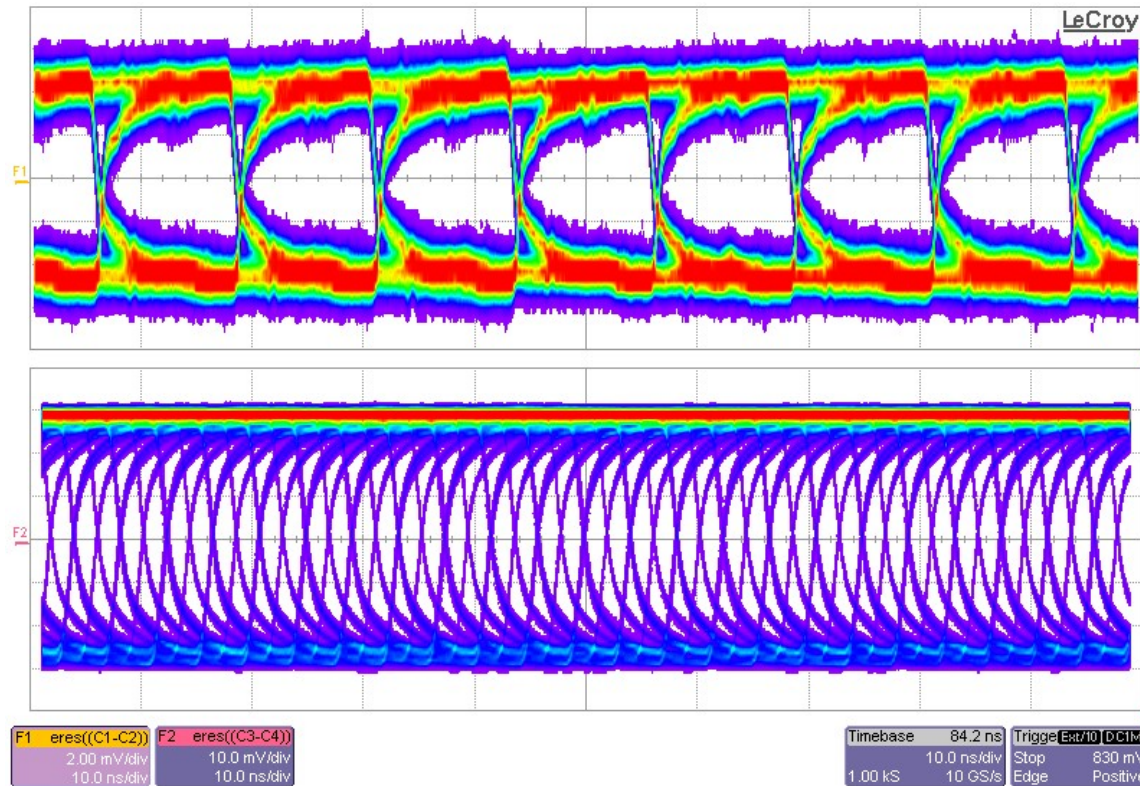
Receiver output signal

$V_{\text{diff}} = 7.4 \text{ mV @ } 80 \text{ Mbit/s}$

Scope bandwidth limited to 1 GHz

- 80 Mbit/s and 160 Mbit/s
- Bit Error Rate  $< 10^{-11}$
- Receiver design error (time asymmetry)  $\rightarrow$  amplitude at receiver  $> 35 \text{ mV @ } 160 \text{ MHz}$

# Crosstalk



$V_{\text{diff}} = 9 \text{ mV @ } 80 \text{ Mbit/s}$

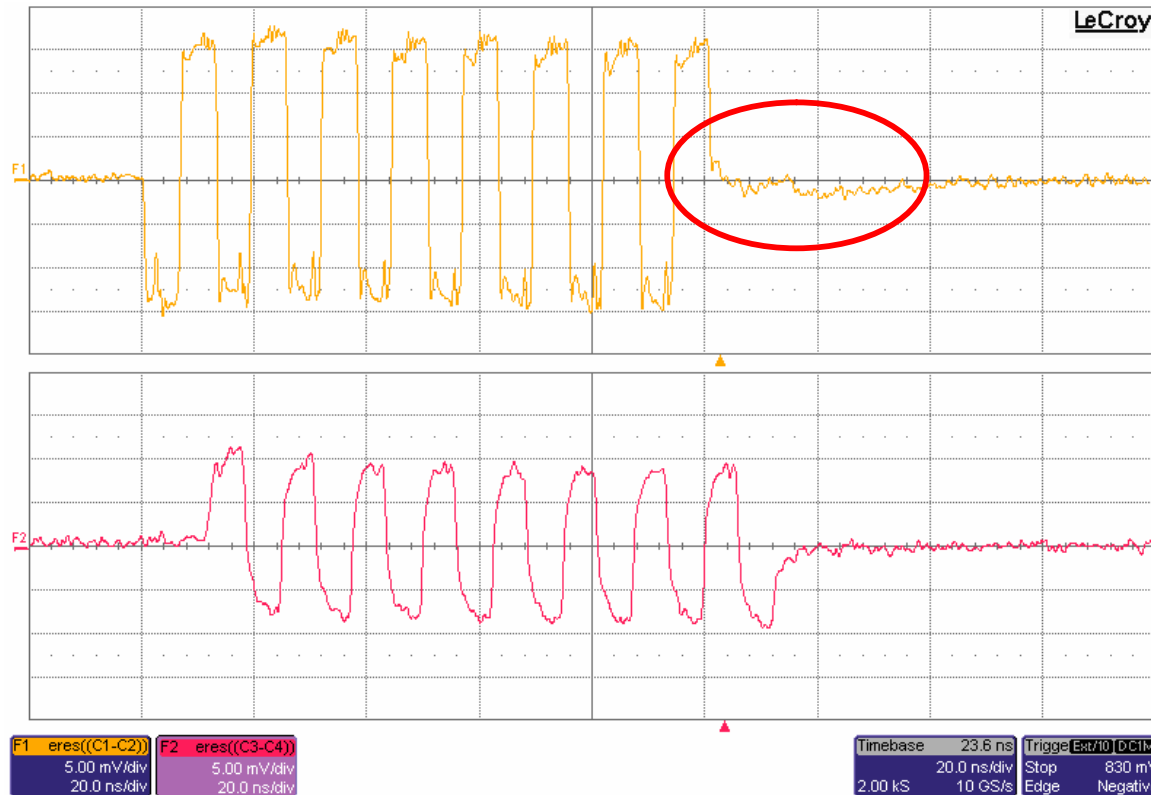
Scope bandwidth limited to 1 GHz

parallel line signal  
(asynchronous)

$V_{\text{diff}} = 56 \text{ mV}$

- 80 Mbit/s and 160 Mbit/s (with higher level)
- No difference in bit error rate visible with/without disturbing signal
- very robust for crosstalk (twisted cable, high capacitance cable)

# Tranceiver switching Time



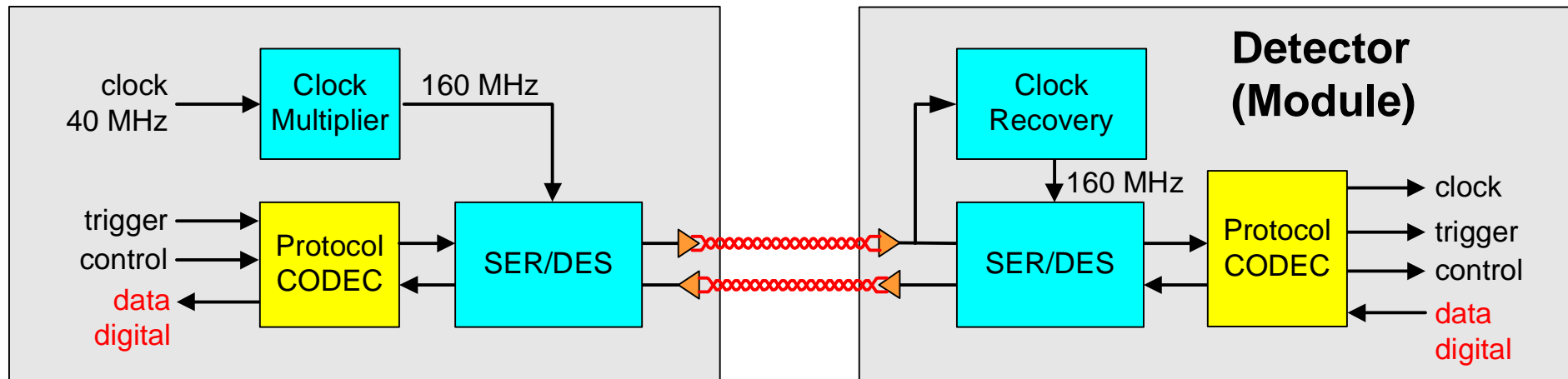
$V_{diff} = 27$  mV at transmitter

$V_{diff} = 18$  mV at receiver (line end)

- Data direction switching at 160 Mbit/s
- Line length: 2 m
- minimal delay for line stabilization (less than 1 signal round trip in a 2 m line)



# Data protocol



Implemented on the Chip (blue)

- Clock multiplier (PLL)
- Clock recovery (PLL)
- Serializer/Deserializer SER/DES

To implement on the FPGA (yellow)

- Bit coding
- Protocol

Different cable configuration

- 1 cable, bidirectional ↔
- 2 cables, unidirectional → ←
- 2 cables, bidirectional ↔ ↔



# Conclusions, Outlook

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- 160 Mbit/s is tested
  - Less than 10 pJ per bit
  - Power for module data link: 2.4 mW (+PLL) new, 26 mW existing
  - No crosstalk problems, it is possible to bundle the unshielded cable
- 
- Tests with 320 Mbit/s
  - Tests with other wires
  - Clock recovery, PLL, VCO
  - Run different data protocols (data packets)